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Vishay Siliconix

Automotive N-Channel 40 V (D-S) 175 °C MOSFET

Marking code: Q040

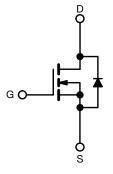
PRODUCT SUMMARY	
V _{DS} (V)	40
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0095
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0110
I _D (A)	16
Configuration	Single
Package	PowerPAK 1212-8W

FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



ROHS COMPLIANT HALOGEN FREE



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T	$_{\rm C}$ = 25 °C, unless	s otherwise noted	d)	
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	40	V
Gate-source voltage		V _{GS}	± 20	V
Continuous drain current a	T _C = 25 °C	l _D	16	
Continuous drain current -	T _C = 125 °C		16	
Continuous source current (diode conduction) ^a		I _S	16	Α
Pulsed drain current b		I _{DM}	64	
Single pulse avalanche current	L = 0.1 mH	I _{AS}	25	
Single pulse avalanche energy	L = 0.1 mn	E _{AS}	31.2	mJ
Maximum power dissipation ^b	T _C = 25 °C	P _D	62.5	W
waximum power dissipation ~	T _C = 125 °C	r _D	20	VV
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) e, f			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount c	R_{thJA}	81	°C/W
Junction-to-case (drain)		R_{thJC}	2.4	C/VV

Notes

- a. Package limited
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- c. When mounted on 1" square PCB (FR4 material)
- d. Parametric verification ongoing
- e. See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8W is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- f. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



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SPECIFICATIONS ($T_C = 25$ °C, u	nless otherv	vise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS}	= 0, I _D = 250 μA	40	-	-	\/
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	1.5	2.0	2.5	v
Gate-source leakage	I _{GSS}	V _{DS} =	$0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 40 V	-	-	1	
Zero gate voltage drain current	I_{DSS}	$V_{GS} = 0 V$	V _{DS} = 40 V, T _J = 125 °C	-	-	50	μΑ
		$V_{GS} = 0 V$	V _{DS} = 40 V, T _J = 175 °C	-	-	150	
On-state drain current a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	20	-	-	Α
		V _{GS} = 10 V	I _D = 10 A	-	0.0081	0.0095	
	Б	V _{GS} = 10 V	I _D = 10 A, T _J = 125 °C	=	-	0.0152	
Drain-source on-state resistance a	R _{DS(on)}	V _{GS} = 10 V	I _D = 10 A, T _J = 175 °C	=	-	0.0190	V 0 nA μA 0 A 055 62 Ω 10 S 0 pF 1 nC 3 Ω 7 ns 3 A
		V _{GS} = 4.5 V	I _D = 10 A	=	0.0095	0.0110	
Forward transconductance b	9 _{fs}	V _{DS}	= 15 V, I _D = 10 A	-	62	-	S
Dynamic ^b							
Input capacitance	C _{iss}			=-	1565	2350	
Output capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	=-	193	290	pF
Reverse transfer capacitance	C _{rss}			=-	68	102	
Total gate charge ^c	Qg			=	27	40	
Gate-source charge ^c	Q_{gs}	V _{GS} = 10 V	$V_{DS} = 20 \text{ V}, I_D = 4 \text{ A}$	=	5	-	nC
Gate-drain charge ^c	Q_{gd}			-	3.6	-	
Gate resistance	R_g		f = 1 MHz	3.6	8.0	12.8	Ω
Turn-on delay time ^c	t _{d(on)}			-	7.8	11.7	
Rise time ^c	t _r	V_{DD}	= 20 V, $R_L = 5 \Omega$	-	2.4	3.6	
Turn-off delay time ^c	t _{d(off)}	$I_D \cong 4 A, V$	$I_{\rm GEN}$ = 10 V, $R_{\rm g}$ = 1 Ω	-	38	57	ris
Fall time ^c	t _f			=-	7.2	10.8	
Source-Drain Diode Ratings and Charac	teristic ^b	•					
Pulsed current ^a	I _{SM}			-	-	64	Α
Forward voltage	V_{SD}	I _F =	10 A, V _{GS} = 0 V	=	0.82	1.1	V
Body diode reverse recovery time	t _{rr}			-	18	36	ns
Body diode reverse recovery charge	Q _{rr}		^ di/d+ = 100 ^ /···	-	12	24	nC
Reverse recovery fall time	t _a	$I_F = 5$	A, di/dt = 100 A/μs	-	11	-	
Reverse recovery rise time	t _b			-	6	-	ris
Body diode peak reverse recovery current	I _{RM(REC)}			-	-1.3	-3	Α

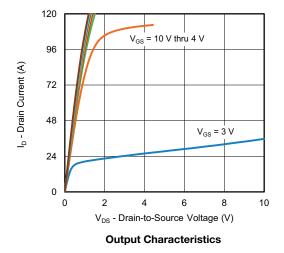
Notes

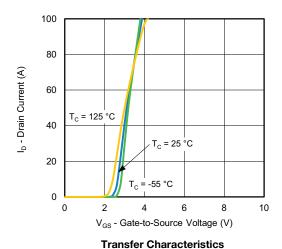
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

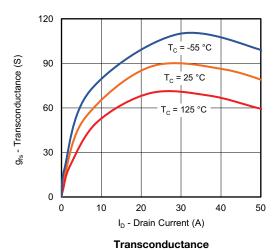
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

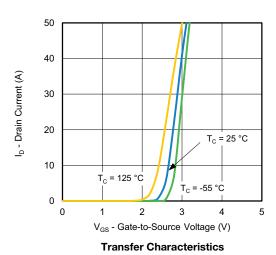


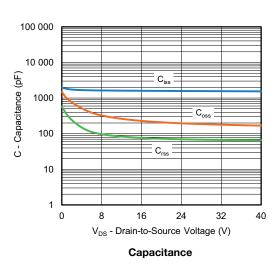
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

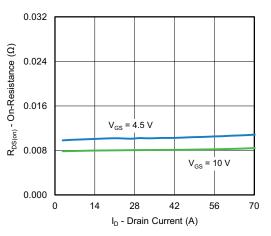








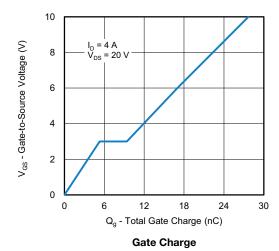


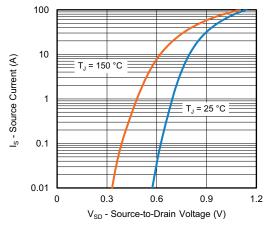


On-Resistance vs. Drain Current

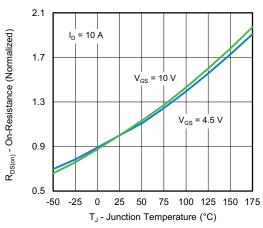


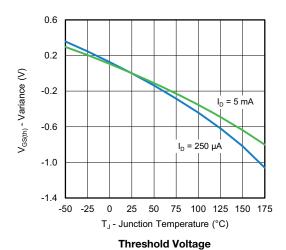
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



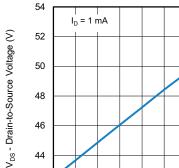


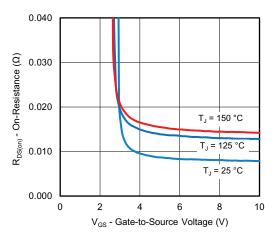
Source Drain Diode Forward Voltage





On-Resistance vs. Junction Temperature





48 46 46 46 42 42 42 42 42 450 -25 0 25 50 75 100 125 150 175 T_J - Junction Temperature (°C)

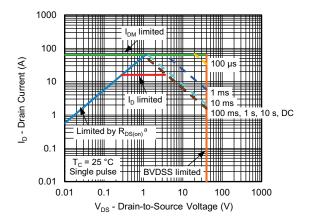
On-Resistance vs. Gate-to-Source Voltage

Drain Source Breakdown vs. Junction Temperature

For technical questions, contact: automoste



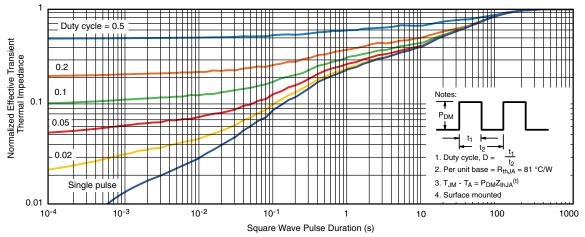
THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



Safe Operating Area

Note

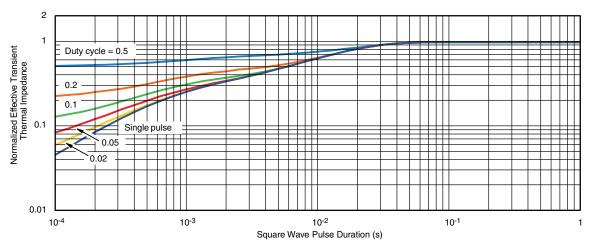
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

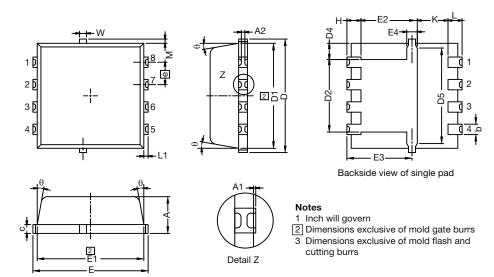
- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg277038.



PowerPAK® 1212-8W Case Outline



DIM		MILLIMETERS			INCHES		
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.97	1.04	1.12	0.038	0.041	0.044	
A1	0	=	0.05	0	-	0.002	
A2	0	-	0.13	0	-	0.005	
b	0.23	0.30	0.41	0.009	0.012	0.016	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	3.20	3.30	3.40	0.126	0.130	0.134	
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
D4		0.47 typ.			0.0185 typ.		
D5		2.3 typ.		0.090 typ.			
Е	3.20	3.30	3.40	0.126	0.130	0.134	
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	1.75	1.85	1.98	0.069	0.073	0.078	
E4		0.34 typ.		0.013 typ.			
е		0.65 BSC.		0.026 BSC			
K		0.86 typ.		0.034 typ.			
Н	0.30	0.41	0.51	0.012	0.016	0.020	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М		0.125 typ.			0.005 typ.		

DWG: 6032



RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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